#### TEL62/TDCB HW status



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TDAQ WG Meeting

Ferrara September 2, 2014

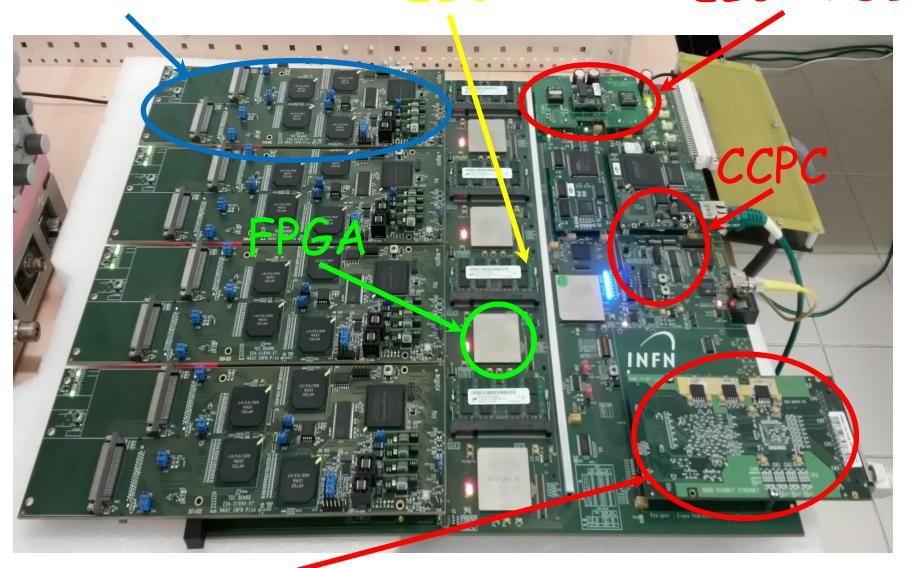




TDCB

TEL62

#### TEL62-PSB



QGBE -

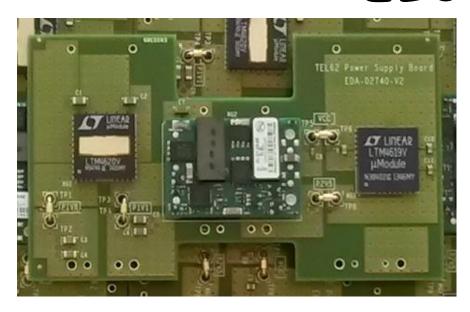
#### TDCB

- All PCBs produced (100 pcs)
- First batch 10 boards:
  - > Assembled and tested with no issues
- Second batch 90 boards:
  - >50 assembled & tested (no issues)
  - >40 assembled & under test
- 50 TDCBs sent to CERN (July/August)

### TEL62 Components & Mezzanine

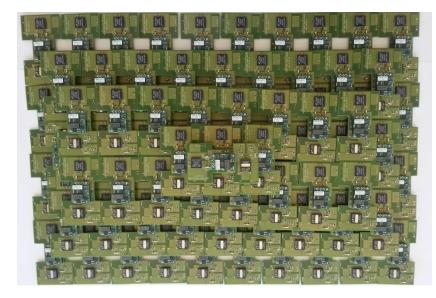
- EP3SL200F1152C4N (new FPGAs):
  - >364 pcs ready for assembly
  - > 120 pcs ordered and will be delivered to CERN this week (September 4)
- CCPC and RAM:
  - > All the CCPC (100 pcs) and a part of CCPC-RAM (76 pcs) are in stock (Pisa)
  - >24 pcs CCPC-RAM in order (Roma Tor Vergata)
- QGBE (40 pcs):
  - > 23 pcs sent to CERN:
    - 9 pcs (Pisa)
    - -14 pcs (CERN)
  - >17 pcs (Roma Tor Vergata)

#### TEL62-PSB



 TEL62-PSB is the mezzanine providing 1.1V, 1.8V and 2.5V to TEL62

 100 pcs assembled and tested with no issues



## TEL62 Production (1)

 TEL62-V3 production (PCB and Board Assembly) has been assigned to a new firm (Link Engineering)

- All PCBs produced (94 pcs)
  - ➤ Board Assembly has been divided in 5 batches

# TEL62 Production (2)

- First batch (5 boards, Dec 2013):
  - >3 boards: OK
  - ≥1 board: OK
    - had a problem on PPO-FPGA (BST), solved with replacement
  - ≥1 board:
    - had a problem on PPO-FPGA (BST), solved with FPGA replacement
    - -5VA shorted with GND, sent to Link Engineering for repair

# TEL62 Production (3)

- Second batch (10 boards, May 2014):
  - >7 boards: OK
  - > 3 boards: OK
    - QDR problems with TDSPY but no problems with BST
    - After various studies a firmware problem was detected and solved
- Third batch (9 boards, July 2014): OK

### TEL62 Production (4)

- Fourth batch (31 boards, Sept 2014):
  - > Will arrive in Pisa next week

- Final batch (39 boards):
  - > The company will start the assembly as soon as FPGAs will be available

 Testing to be done together Roma Tor Vergata

## TEL62 Production (5)

- In the past (old firm, version 2): 50% suffered of FPGAs soldering issues (1):
  - 4/16 NOT USABLE
  - 4/16 with FPGA(s) replacement
- Now: soldering issues have been mitigated ©
  - Only 2/24 board with FPGAs replacements (only on the 1<sup>st</sup> batch)
- 15 TEL62 sent to CERN (June/August)
- 1. https://twiki.cern.ch/twiki/bin/view/NA62/TDAQTel62Board

